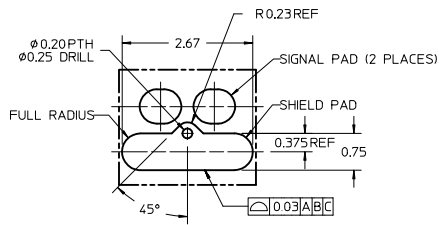
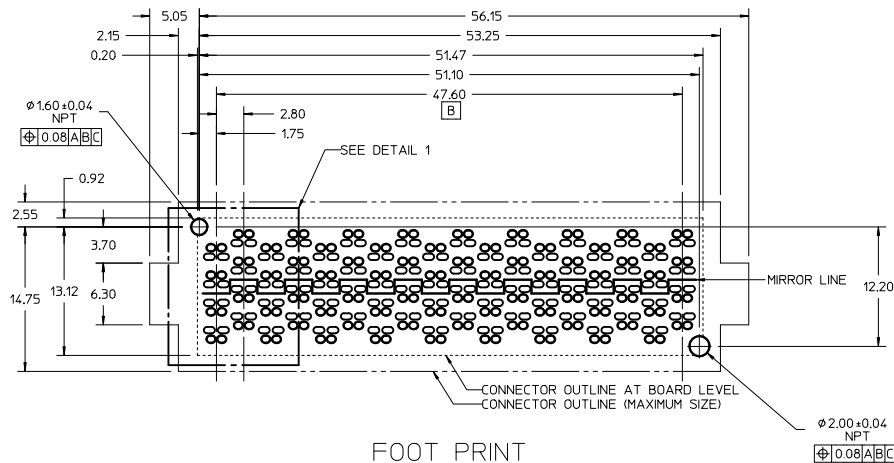


- NOTES:
- HOUSING MATERIAL: LCP; GLASS FILLED, UL 94V-0, BLACK
CONTACT MATERIAL: HIGH PERFORMANCE COPPER ALLOY
SOLDER CHARGE: LEAD FREE SOLDER ALLOY
 - FINISH:
CONTACTS: SELECT GOLD: 30 MICHES MIN ON CONTACT AREA,
AND 2MICHES MIN ON SOLDERABLE PORTION
OF SOLDER TAILS, OVER 50 MICHES MIN NICKEL OVERALL.
 - PRODUCT SPECIFICATION: PS-170807-0001
 - PACKAGING SPECIFICATION: PK-170807-0001
 - APPLICATION SPECIFICATION: AS-170807-0001



DETAIL 4
SCALE 20:1

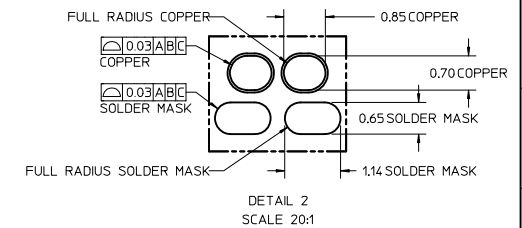
(SOLDER MASK REMOVED TO REVEAL SHIELD TRACE)



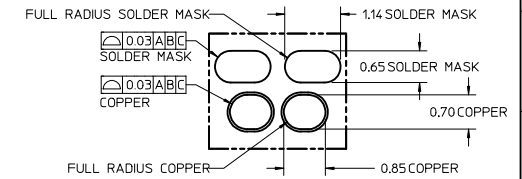
FOOT PRINT

FOOT PRINT NOTES:

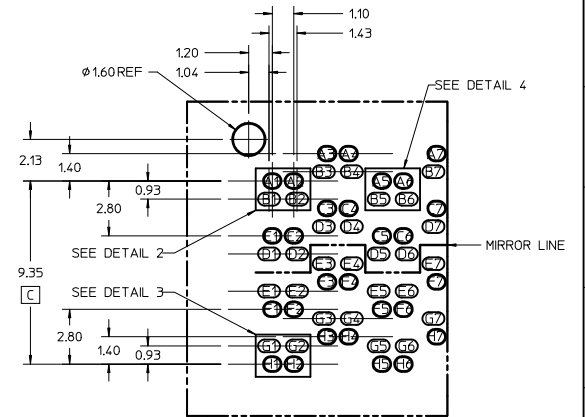
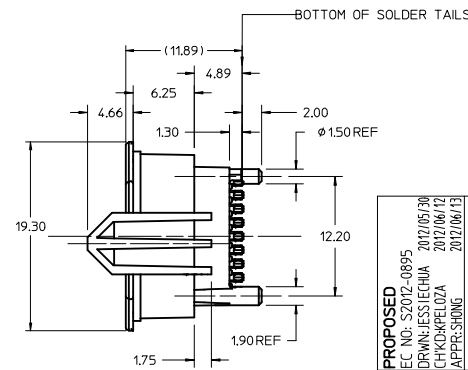
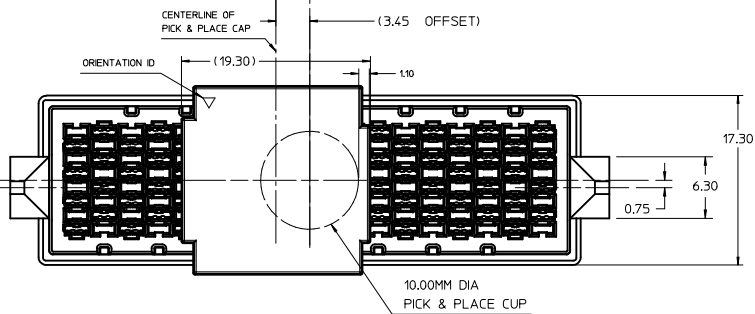
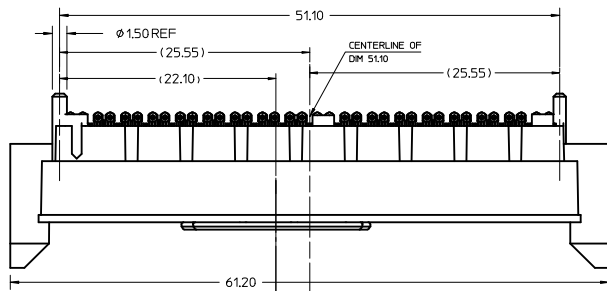
- DATUM -A- IS THE TOP OF THE PCB.
- ALL DIMENSIONS ARE BASICS.
- ROW A, C, F, AND H PADS (SIGNAL PADS) ARE COPPER DEFINED.
- ROW B, D, E, AND G PADS (SHIELD PADS) ARE SOLDER MASK DEFINED.



DETAIL 2
SCALE 20:1



DETAIL 3
SCALE 20:1



DETAIL 1
SCALE 8:1
(NUMBERING SCHEME SHOWN)

PROPOSED EC NO: SZ2012-0895 UJ DRWN: JESSIE CHIA CHYKPELOZA APPR: SHONG 2012/05/30 2012/06/12 2012/06/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	▽=0	mm INCH	DRAWN BY KPELOZA	DATE 2011/06/07	TITLE RECEPTACLE 2MM WIPE, 8MM, 4X18 NEUTRINO, MIRRORED	MOLEX INCORPORATED
	▽=0	4 PLACES ± --- ± ---	CHECKED BY KPELOZA	DATE 2011/06/07	MATERIAL NO. 1708140009	
	▽=0	3 PLACES ± --- ± --- 2 PLACES ± 0.15 ± --- 1 PLACE ± --- ± ---	APPROVED BY JCOMERCI	DATE 2011/06/08		DOCUMENT NO. SD-170814-0009
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		ANGULAR ±1/2°	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			